

	Type	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	389	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with maintenance\$1 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 11:14	
2	BRS	15	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:40	
3	BRS	27	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same prevent\$3 with maintenance\$1 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:41	
4	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:41	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	3	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:42	
6	BRS	2	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3 and (evalu\$3 or validat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:43	
7	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3 and (evalu\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:43	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
8	BRS	10	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) and prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3 and (evalu\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:43	
9	BRS	8	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) and prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3 and (evalu\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3) with (status or state\$1 or condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:45	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
10	BRS	6	(semiconductor\$1 or wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1)) and prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3 and (evalu\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3) with (status or state\$1 or condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:48	
11	BRS	2	(semiconductor\$1 or wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and prevent\$3 with maintenance\$1 same manag\$6 and parameter\$1 with process\$3 and (evalu\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3) with (status or state\$1 or condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:53	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
12	BRS	2	(semiconductor\$1 or wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and prevent\$3 with maintenance\$1 same manag\$6 and parameter\$1 with process\$3 and (evalu\$3 or validat\$3) with tim\$3 with cost\$3 and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3) with (status or state\$1 or condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:15	
13	BRS	277	702/184.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:24	
14	BRS	477	700/95.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:16	
15	BRS	243	700/96.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:16	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
16	BRS	40	(semiconductor\$1 or wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and prevent\$3 with maintenance\$1 and parameter\$1 with process\$3 and (evaluat\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3) with (status or state\$1 or condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:18	
17	BRS	1178	702/176,177,178,184,187.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:06	
18	BRS	4501	700/12,14,17,19,108,121,174,175,176,178,180.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:27	
19	BRS	5382	700/12,14,17,19,108,117,121,174,175,176,178,180.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:27	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
20	BRS	29	(700/12,14,17,19,108,117,121,174,175,176,178,180.ccls.) and semiconductor\$1 with process\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:28	
21	BRS	0	(700/12,14,17,19,108,117,121,174,175,176,178,180.ccls.) and semiconductor\$1 with process\$3 with maintenance\$1 and (validat\$3 or evaluat\$3 or estimat\$3) with tim\$3 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:29	
22	BRS	0	semiconductor\$1 with process\$3 with maintenance\$1 and (validat\$3 or evaluat\$3 or estimat\$3) with tim\$3 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:29	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
23	BRS	5	(700/12,14,17,19,108,117,121,174,175,176,178,180.ccl s.) and semiconductor\$1 with process\$3 and prevent\$3 with maintenance\$1 and (validat\$3 or evaluat\$3 or estimat\$3) with tim\$3 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:34	
24	BRS	0	(700/12,14,17,19,108,117,121,174,175,176,178,180.ccl s.) and semiconductor\$1 same process\$3 with parameter\$1 and prevent\$3 with maintenance\$1 and (validat\$3 or evaluat\$3 or estimat\$3) with tim\$3 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:34	
25	BRS	3	semiconductor\$1 same process\$3 with parameter\$1 and prevent\$3 with maintenance\$1 and (validat\$3 or evaluat\$3 or estimat\$3) with tim\$3 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:45	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
26	BRS	0	semiconductor\$1 with equipment\$1 with product\$1 same prevent\$3 with maintenance\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:53	
27	BRS	15	semiconductor\$1 with equipment\$1 and semiconductor\$1 with product\$1 and prevent\$3 with maintenance\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:47	
28	BRS	5	semiconductor\$1 with equipment\$1 with semiconductor\$1 with product\$1 and prevent\$3 with maintenance\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:48	
29	BRS	1	semiconductor\$1 with equipment\$1 with semiconductor\$1 with product\$1 and prevent\$3 with maintenance\$1 and process\$3 with parameter\$1 and cost with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:50	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
30	BRS	7	semiconductor\$1 with equipment\$1 and semiconductor\$1 with product\$1 and prevent\$3 with maintenance\$1 and process\$3 with parameter\$1 and cost with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:50	
31	BRS	6	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$1 with product\$1 same prevent\$3 with maintenance\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:53	
32	BRS	6	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$1 with product\$1 same prevent\$3 with maintenance\$1 and process\$3 with parameter\$1 and cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:54	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
33	BRS	2	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$1 with product\$1 same prevent\$3 with maintenance\$1 and process\$3 with parameter\$1 and (estimat\$3 or evaluat\$3 or validat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:55	
34	BRS	11	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$1 with maintenance\$1 and process\$3 with parameter\$1 and equipment\$1 with parameter\$1 and maintenance\$1 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:59	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
35	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with maintenance\$1 with manag\$6 and (evaluat\$3 or estimat\$3 or validat\$3) with cost\$3 with tim\$3 with maintenance\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:01	
36	BRS	1	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with maintenance\$1 and (evaluat\$3 or estimat\$3 or validat\$3) with cost\$3 with tim\$3 with maintenance\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:02	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
37	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC or ICs or (integrated adj circuit\$1)) with maintenance\$1 and (evaluat\$3 or estimat\$3 or validat\$3) with cost\$3 with tim\$3 with maintenance\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:02	
38	BRS	1779	705/7,11.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:04	
39	BRS	3388	702/84,176,177,178,182,183,184,185,187.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:07	
40	BRS	34	(702/84,176,177,178,182,183,184,185,187.ccls.) and semiconductor\$1 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:08	
41	BRS	7	(702/84,176,177,178,182,183,184,185,187.ccls.) and semiconductor\$1 with maintenance\$1 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:08	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
42	BRS	0	(702/84,176,177,178,182,183,184,185,187.ccls.) and semiconductor\$1 with maintenance\$1 with manag\$6 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:09	
43	BRS	0	("702"/\$.ccls.) and semiconductor\$1 with maintenance\$1 with manag\$6 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:09	
44	BRS	0	("705"/\$.ccls.) and semiconductor\$1 with maintenance\$1 with manag\$6 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:09	
45	BRS	1	("705"/\$.ccls.) and semiconductor\$1 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:09	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
46	BRS	0	("700"/\$.ccls.) and semiconductor\$1 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:09	
47	BRS	1	("705"/\$.ccls.) and semiconductor\$1 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:23	
48	BRS	5	semiconductor\$1 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:12	
49	BRS	7	semiconductor\$1 same prevent\$3 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:16	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
50	BRS	10	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) same prevent\$3 with maintenance\$1 and (evaluata\$3 or validat\$3 or estimat\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:17	
51	BRS	11	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) same prevent\$3 with maintenance\$1 and (evaluata\$3 or validat\$3 or estimat\$3 pr predict\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:17	
52	BRS	68	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) and prevent\$3 with maintenance\$1 and (evaluata\$3 or validat\$3 or estimat\$3 pr predict\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:17	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
53	BRS	3	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) and prevent\$3 with maintenance\$1 with manag\$6 and (evaluat\$3 or validat\$3 or estimat\$3 pr predict\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:17	
54	BRS	1	"6327521".PN.	USPAT; USOCR	2005/05/23 13:19	
55	BRS	1	"6192287".PN.	USPAT; USOCR	2005/05/23 13:19	
56	BRS	1	"6090632".PN.	USPAT; USOCR	2005/05/23 13:20	
57	BRS	1	"5940300".PN.	USPAT; USOCR	2005/05/23 13:20	
58	BRS	1	"5910011".PN.	USPAT; USOCR	2005/05/23 13:21	
59	BRS	1	"4720806".PN.	USPAT; USOCR	2005/05/23 13:21	
60	BRS	1	"5327349".PN.	USPAT; USOCR	2005/05/23 13:21	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
61	BRS	4	("705"/\$.ccls.) and (wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:24	
62	BRS	0	("705"/\$.ccls.) and (wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:25	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
63	BRS	0	("705"/\$.ccls.) and (wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) with equipment\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:25	
64	BRS	0	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) with (workpiece\$1 or equipment\$1) and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:26	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
65	BRS	0	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3 with prevent\$3 with maintenanc\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:26	
66	BRS	1	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3 same prevent\$3 with maintenanc\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:26	
67	BRS	1	(piece\$1 or workpiece\$1) with (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with equipment\$1 same prevent with maintenanc\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:33	
68	IS&R	2	("4860571").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:33	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
69	BRS	0	"6782302".uref.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:54	
70	BRS	0	prevent\$3 with maintenance\$1 with (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:57	
71	BRS	0	prevent\$3 with maintenance\$1 same (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:57	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
72	BRS	17	prevent\$3 with maintenance\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:59	
73	BRS	2	prevent\$3 with maintenance\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) with equipment\$1 and cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:00	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
74	BRS	0	prevent\$3 with maintenance\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) with equipment\$1 with product\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:01	
75	BRS	0	prevent\$3 with maintenance\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with product\$1 with (piece\$1 or workiece\$1) same equipment\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:01	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
76	BRS	55	prevent\$3 with maintenance\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) and equipment\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:02	
77	BRS	1	prevent\$3 with maintenance\$1 with (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) and equipment\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:02	
78	BRS	7	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workpiece\$1) with equipment\$1 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:07	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
79	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workpiece\$1) with equipment\$1 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:06	
80	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workpiece\$1) with equipment\$1 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:06	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
81	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workpiece\$1) with equipment\$1 same prevent\$3 with maintenanc\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:06	
82	BRS	4	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with prevent\$3 with maintenanc\$1 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:09	
83	BRS	4	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with prevent\$3 with maintenanc\$1 same manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:09	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
84	BRS	55	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with prevent\$3 with maintenace\$1 and manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:09	
85	BRS	49	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with prevent\$3 with maintenace\$1 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:10	
86	BRS	0	semicopnductor\$1 with prevent\$3 with maintenace\$1 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:10	
87	BRS	29	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenace\$1 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:21	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
88	BRS	7	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and (evaluat\$3 or validat\$3 or estimat\$3 or predict\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:18	
89	BRS	1740	451/1,8.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:18	
90	BRS	11	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:22	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
91	BRS	2	(semicopnductor\$1 or wafer\$1 or IC or ICS or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 with manag\$6 and (semicopnductor\$1 or wafer\$1 or IC or ICS or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICS or (integrated adj circuit\$1)) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
92	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 with manag\$6 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:24	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
93	BRS	6	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:31	/
94	BRS	343	438/5.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:26	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
95	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and process\$3 with parameter\$1 and user\$1 with interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:31	
96	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and user\$1 with interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
97	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 with interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:32	
98	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 same interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:32	
99	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and user\$1 with interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:33	
100	BRS	7	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:22	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
101	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and computer\$1 with interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:34	
102	BRS	1	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and interface\$1 with (record\$3 or sav\$3 or stor\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:39	
103	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and interface\$1 with database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:39	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
104	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with cost\$3 with prevent\$3 with maintenanc\$1 with cost\$3 with (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:23	
105	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with prevent\$3 with maintenanc\$1 with cost\$3 same (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:24	
106	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with prevent\$3 with maintenanc\$1 with cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:24	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
107	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same prevent\$3 with maintenanc\$1 with cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:25	
108	BRS	46	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same prevent\$3 with maintenanc\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:25	
109	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same prevent\$3 with maintenanc\$1 same cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:25	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
110	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with cost\$3 same prevent\$3 with maintenanc\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:26	
111	BRS	2	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with qualit\$3 same prevent\$3 with maintenanc\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:26	
112	BRS	48	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with warn\$3 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 11:14	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
113	BRS	1	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with warn\$3 with manag\$6 and (stor\$3 or sav\$3 or record\$3) with process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 11:17	
114	BRS	2	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with (diagnos\$3 or warn\$3) with manag\$6 and (stor\$3 or sav\$3 or record\$3) with process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 11:18	
115	BRS	4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same (diagnos\$3 or warn\$3) with manag\$6 and (stor\$3 or sav\$3 or record\$3) with process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 11:19	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
116	BRS	41	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with manag\$6 and (stor\$3 or sav\$3 or record\$3) with process\$3 with parameter\$1 and (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 11:23	
117	BRS	19	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with manag\$6 and (stor\$3 or sav\$3 or record\$3) with process\$3 with parameter\$1 and (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 and (warn\$3 or notice or inform\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 11:44	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
118	BRS	4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with manag\$6 and (stor\$3 or sav\$3 or record\$3) with process\$3 with parameter\$1 and (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 and (warn\$3 or notice or inform\$2) and (piece\$1 or workpiece\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:10	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
119	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with manag\$6 and (stor\$3 or sav\$3 or record\$3) with (condition\$1 or status or state\$1) with process\$3 with parameter\$1 and (evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 and (warn\$3 or notice or inform\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:13	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
120	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with manag\$6 and (database or file\$1 or stor\$3 or sav\$3 or record\$3) with (condition\$1 or status or state\$1) with process\$3 with parameter\$1 and (evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 and (warn\$3 or notice or inform\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:14	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
121	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with manag\$6 and (database or file\$1 or stor\$3 or sav\$3 or record\$3) with (condition\$1 or status or state\$1) with process\$3 with parameter\$1 and (evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:14	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
122	BRS	3	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with manag\$6 and (database or file\$1 or stor\$3 or sav\$3 or record\$3) with (condition\$1 or status or state\$1) with process\$3 with parameter\$1 and (evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:15	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
123	BRS	4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same manag\$6 and (database or file\$1 or stor\$3 or sav\$3 or record\$3) with (condition\$1 or status or state\$1) with process\$3 with parameter\$1 and (evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:18	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
124	BRS	4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same manag\$6 and (database or file\$1 or stor\$3 or sav\$3 or record\$3) with (condition\$1 or status or state\$1) with process\$3 with parameter\$1 and (evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:18	
125	BRS	48	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with warn\$3 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
126	BRS	1	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with warn\$3 with manag\$6 and (condition\$1 or status or state\$1) with process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:23	
127	BRS	1	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with warn\$3 with manag\$6 and (condition\$1 or status or state\$1) same process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:22	
128	BRS	1	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with warn\$3 with manag\$6 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:22	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
129	BRS	3	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with warn\$3 with manag\$6 and (condition\$1 or status or state\$1) with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:23	
130	BRS	5	"700"/\$.ccls. and (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same warn\$3 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:26	
131	BRS	534	"700"/\$.ccls. and (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) and warn\$3 and manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:26	
132	BRS	9	"700"/\$.ccls. and (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same warn\$3 same manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:30	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
133	BRS	195	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same warn\$3 same manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/01 12:30	
134	BRS	48	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with warn\$3 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:00	
135	IS&R	2	("6782302").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 10:29	
136	BRS	16	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipments with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:01	
137	BRS	2	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipments with parameter\$1 and (notice\$1 or warn\$3 or alarm\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:02	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
138	BRS	68	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$ with parameter\$1 and (notice\$1 or warn\$3 or alarm\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:03	
139	BRS	24	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$ with parameter\$1 and warn\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:02	
140	BRS	1	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$ with parameter\$1 and warn\$3 and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:03	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
141	BRS	10	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipments\$ with parameter\$1 and (notice\$1 or warn\$3 or alarm\$1) and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:05	
142	BRS	8	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipments\$ with parameter\$1 and (notice\$1 or warn\$3 or alarm\$1) and equipments and record\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:06	
143	BRS	15	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipments and process\$3 with parameter\$1 and (notice\$1 or warn\$3 or alarm\$1) and record\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 11:55	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
144	BRS	14	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipments and process\$3 with parameter\$1 and (notice\$1 or warn\$3 or alarm\$1) and (database\$1 or record\$3 or stor\$4 or sav\$3) and interface\$1.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:38	
145	BRS	21	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipments and process\$3 with parameter\$1 and equipment\$2 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:39	
146	BRS	823	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipments and process\$3 with parameter\$1 and equipment\$2 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:39	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
147	BRS	66	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$ and (compar\$4 or differen\$2) with process\$3 with parameter\$1 with equipment\$2 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:40	
148	BRS	6	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (compar\$4 or differen\$2) with process\$3 with parameter\$1 with equipment\$2 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:47	
149	BRS	3	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and t-test	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:48	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
150	BRS	24	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and one-way	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:16	
151	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and one-way with (analys\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:48	
152	BRS	3	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and one with way with (analys\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:50	
153	BRS	22	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and anova	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 16:01	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
154	BRS	4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same product\$1 with qualit\$3 and anova with t-test	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 15:56	
155	BRS	3	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and anova and database\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 16:13	
156	BRS	10	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same product\$1 with qualit\$3 and anova and database\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 16:21	
157	BRS	114	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with test\$3 with qualit\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 16:23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
158	BRS	6	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with test\$3 with qualit\$3 with parameter\$1 and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 16:25	
159	BRS	27	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with test\$3 with qualit\$3 with parameter\$1 and database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 16:25	
160	BRS	17	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with test\$3 with qualit\$3 with parameter\$1 and database and (inspect\$3 or estimat\$3 or evaluat\$3 or validat\$3 or predict\$3) with (analys\$3 or analyz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/06 16:26	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
161	BRS	110	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and equipment\$1 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:17	
162	BRS	1	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1 adj parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:21	
163	BRS	4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and equipment\$1 adj parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:18	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
164	BRS	6	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:22	
165	BRS	6	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1 with parameter\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:50	
166	IS&R	2	("6449524").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:28	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
167	BRS	65	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:41	
168	BRS	6	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1 and (estimat\$3 or validat\$3 or evaluat\$3 or predict\$3) with qualit\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:30	
169	BRS	6	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:41	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
170	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1 with parameter\$1 and process\$3 with parameter\$1 and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:50	
171	BRS	8	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1 and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:54	
172	BRS	65	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:54	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
173	BRS	18	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1 and database\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:55	
174	BRS	4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) with measur\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 10:59	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
175	BRS	17	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) and (predict\$3 or inspect\$3 or estimat\$3 or validat\$3 or evaluat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:07	
176	BRS	4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) and (predict\$3 or inspect\$3 or estimat\$3 or validat\$3 or evaluat\$3) and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:08	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
177	BRS	9	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) and (predict\$3 or inspect\$3 or estimat\$3 or validat\$3 or evaluat\$3) and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:09	
178	BRS	9	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (condition\$1 or status or state\$1) with equipment\$1 and database\$1 and (record\$3 or stor\$3 or sav\$3) and (predict\$3 or inspect\$3 or estimat\$3 or validat\$3 or evaluat\$3) and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:12	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
179	BRS	76	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with equipment with (parameter\$1 or measur\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:12	
180	BRS	51	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with equipment with (parameter\$1 or measur\$6) and (record\$3 or stor\$3 or sav\$3 or database) with process\$3 with (parameter\$1 or measur\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:13	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
181	BRS	24	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with equipment with (parameter\$1 or measur\$6) and (record\$3 or stor\$3 or sav\$3 or database) with process\$3 with (parameter\$1 or measur\$6) and (compar\$4 or differen\$2) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:14	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
182	BRS	15	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (record\$3 or stor\$3 or sav\$3 or database) with equipment with (parameter\$1 or measur\$6) and (record\$3 or stor\$3 or sav\$3 or database) with process\$3 with (parameter\$1 or measur\$6) and (compar\$4 or differen\$2) with equipment\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 16:04	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
183	BRS	2	(record\$3 or stor\$3 or sav\$3 or database) with equipment with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3) with test\$3 with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 and statistic\$4 with (analyz\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:26	
184	BRS	4	(record\$3 or stor\$3 or sav\$3 or database) with equipment with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3) with test\$3 with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 and (analyz\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:28	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
185	BRS	4	(record\$3 or stor\$3 or sav\$3 or database) with equipment\$1 with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3) with test\$3 with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 and (analyz\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:29	
186	BRS	4	(record\$3 or stor\$3 or sav\$3 or database) with equipment\$1 with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with test\$3 with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 and (analyz\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:52	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
187	BRS	24	(record\$3 or stor\$3 or sav\$3 or database) with equipment\$1 with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 and (analyz\$3 or analys\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 11:54	
188	BRS	14	(record\$3 or stor\$3 or sav\$3 or database) with equipment\$1 with (status\$2 or condition\$1 or state\$1) and (inspect\$3 or evaluat\$3 or estimat\$3 or validat\$3 or predict\$3) with (semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with product\$1 and (analyz\$3 or analys\$3) and statistic\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 12:40	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
189	BRS	3115	365/201.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/06/07 12:40	
190	BRS	0	365/e21.525.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/06/07 12:44	
191	BRS	1252	257/e21.525.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/06/07 12:44	
192	BRS	47	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (analyz\$3 or analys\$3) with equipment\$1 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/06/07 13:20	
193	BRS	31	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 and (analyz\$3 or analys\$3) with equipment\$1 with parameter\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/06/07 13:20	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
194	BRS	5	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 and (analyz\$3 or analys\$3) with equipment\$1 with parameter\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 13:22	
195	BRS	2	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 with equipment\$1 with parameter\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 13:23	
196	BRS	4	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 with equipment\$1 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 13:23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
197	BRS	8	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 same equipment\$1 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 13:23	
198	BRS	3	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with qualit\$3 with product\$1 and t-test\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 16:07	
199	BRS	58	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with t-test\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 16:06	
200	BRS	155	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) and qualit\$3 with product\$1 and t-test\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/07 16:07	